Reasons for gain degradation with irradiation in LGADs

Gregor Kramberger Jožef Stefan Institute, Ljubljana

Motivation

The key question is: What is the main reason for reduction of effective acceptors and by that of the gain in LGAD?

Options are:

Introduction of deep traps which occupation probabilities are enhanced by larger hole concentration due to multiplication. These compensate the negative space charge of shallow acceptors.

- see F. Rogelio talk at 11th TRENTO workshop in Paris
- see Ranjit talk at 2014 RD50 workshop at CERN
- Removal of initial acceptors (boron) from the p+ layer
 - TCT measurements of the "leg"
 - sharp drop/exponential of gain already at moderate fluences
 - HVCMOS measurements

Note: larger relative trapping effects in LGAD – holes need to drift over the entire depth (not only half on average), hence their trapping probability is larger.

TCAD simulations based on "effective levels" predict the decrease of gain – moderation of the field by trapped holes

Possible scenarios for gain reduction

Before irradiation



thickness (not to scale)

The voltage drop in the amplification layer is around V_{mr} =30 V ("foot"). The gain doesn't increase exponentially with voltage as after the depletion 300 V is required to increase E by 1V/um in the multiplication layer for 300 um thick sensor.

After irradiation



The gain at very high voltages (V_{bias} >> V_{fd}) is reduced due to: initial acceptor (boron) removal or/and but also due to space charge from deep traps:

- Boron insensitive to concentration of free carriers in the bulk!
- Deep traps sensitive to free hole and electron concentrations !

How to change free carrier concentrations?

- 1) The temperature variation of TCT signal, but the exponential term in occupation probability P_t (de-trapping) term changes at the same time as also free carrier concentration (generation current) hard to analyse and see the difference (also ligth absorption is a function of T)
- 2) Keep the detector at given temperature and vary the concentration of free carriers by continuous injection by DC light (CW laser) and probing the gain with TCT

$$P_{t} = \begin{bmatrix} c_{p}p + c_{n}n_{i}\exp(\frac{E_{t} - E_{i}}{k_{B}T}) \\ \frac{1}{c_{n}n + c_{p}n_{i}\exp(\frac{E_{i} - E_{t}}{k_{B}T})} + 1 \end{bmatrix}^{-1} , N_{deep} = \sum_{donors} N_{t}(1 - P_{t}) - \sum_{acceptrors} N_{t}P_{t}$$
ELECTRON INJECTION HOLE INJECTION BACK illumination BACK illumination CW red laser CW red laser CW red laser

Non-irradiated detector (LGAD run 7859)

Back illumination (electron injection)



G. Kramberger et al., "Reasons for gain degradation with irradiations in LGADs", 28th RD50 Workshop, Torino

Non-irradiated detector (LGAD run 7859)

Front illumination (hole injection)



Irradiated detectors

Requirements for good probing:

- fluence small enough to see a clear contribution from holes in TCT signal
- still a sizeable difference in gain to a non-irradiated detector
- measured also with ⁹⁰Sr to estimate the absolute charge



TCT – back illumination and loss of gain

Non-irradiated PIN and LGAD induced currents



Irradiated (2e14 cm⁻²) PIN and LGAD induced currents



G. Kramberger et al., "Reasons for gain degradation with irradiations in LGADs", 28th RD50 Workshop, Torino



G. Kramberger et al., "Reasons for gain degradation with irradiations in LGADs", 28th RD50 Workshop, Torino



• Once the sensor is depleted -> gain reflects the difference in $N_{deep}(p,n)+N_B$.

• At high bias voltages the charge changes with light intensity by max few percent.

07/06/2016

G. Kramberger et al., "Reasons for gain degradation with irradiations in LGADs", 28th RD50 Workshop, Torino

TCT – induced currents for LGAD (2e14 cm⁻²)



- No difference in induced current pulse shapes at high bias voltages for different DC illumination levels for electron injection
- Small difference in induced current for hole injection at the highest intensity – trapped holes moderate the bulk, but have little effect on doping concentration of p⁺ layer
- Similar conclusions for pion irradiated samples (not shown)

How does that compute?

- The contribution of multiplied charge (holes) decreases therefore from around 80000 e to around 26000 e (see below)
- Estimated trapping time of holes is around 10 ns which at duration of current pulse of 5 ns gives a deficit of <15%
- The variation of n,p concentrations in large range makes a difference of of gain max 5%



Reduction of signal by ~55% reduction of gain of holes ~ 70%



The difference of gain can not be explained by deep traps moderating the field or trapping only. Removal of initial boron is required!

How does the "leg" shift correlate with gain?



V_{leg}=26 V is also for R6428 W7 wafer before irradiation!

- ~6 V lower voltage is required for depletion of multiplication region
- Assuming a fully depleted device and ~1 μm wide multiplication region, then one can calculate required over depletion for achieving the same gain as before irradiation. To establish the same field one needs ΔV=E*300 μm

Gain and over depletion



3

5

6

CNM simulations (thanks to Giulio)



6 18 20 22 Φ_{eq} [10¹⁴ cm⁻²]

Conclusions

- The origin of effective loss of acceptors in the multiplication layer of LGAD was examined.
- Red DC light was used to change occupation probabilities of traps to separate contribution from shallow and deep acceptors:
 - □ Large effect on bulk electric field
 - □ Little effect on collected charge at very high voltages
- Deep traps do not influence much the gain of LGAD at very high voltages – deactivation of shallow acceptors should be responsible.
- The decrease of the "leg voltage" roughly agrees with the over depletion need to achieve the same electric field in the multiplication layer